

The logo for Microbond, featuring a stylized blue wave above the word "MICROBOND" in a bold, sans-serif font.

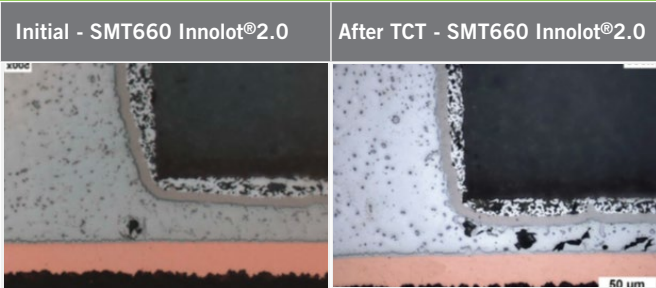
Microbond® SMT660 Innolot®2.0 No-Clean Printing T4 Solder Paste

Microbond® SMT660 Innolot® 2.0 paste stands for highly reliable, high-performance paste with a competitive Total Cost of Ownership (TCO) offering. The next generation of Innolot® alloy offers reduced cost while maintaining the well known features of higher creep resistance, resulting in longer product life cycles at higher operating temperatures. The SMT660 Innolot® 2.0 solder paste performs in the air without additional N₂ during reflow, while keeping defects low, reducing your TCO. This specifically means reduced pin and blowhole behavior, very low BGA voiding and low area voiding.

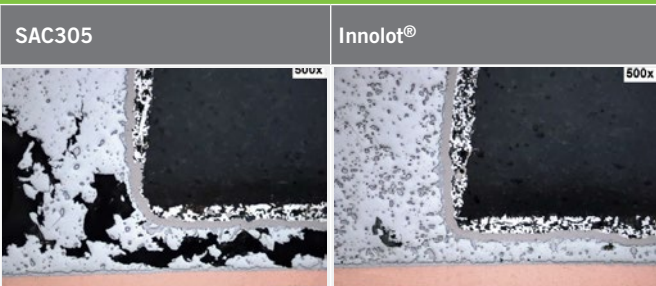
Key Features

- Innolot®2.0 solder pastes solderable in the air with low defects at a reduced cost
- Acrylic-based synthetic resin ensures the stable quality
- Reduced pin and blowhole behavior
- High-reliability alloy and high SIR performance
- Low area voiding
- Halogen zero

Cross section on a 1206 resistor after 2000 hours temperature cycling test from -40 °C to 125 °C



Cross section on a 1206 resistor after 2000 hours temperature cycling test from -40 °C to 125 °C



Product properties Microbond® SMT660 Innolot®2.0

Alloy	Innolot®2.0
Metal content	89%
Halogen content	Halogen zero
Flux classification	No-clean

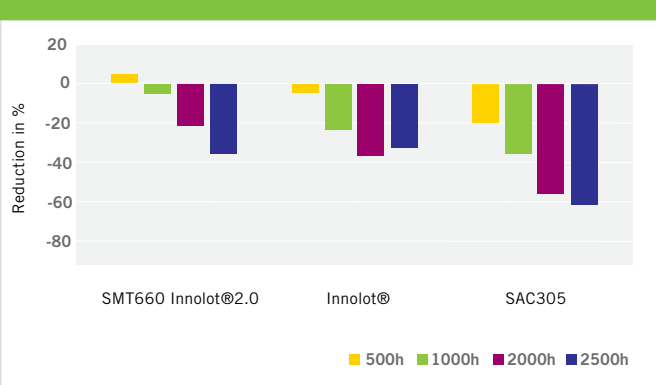
Powder properties

Powder type	Type 4, 20 - 38 µm
Alloy	Sn/Ag1.5/Cu0.7/Sb1.5/Bi3/X
Melting point	212 - 222 °C

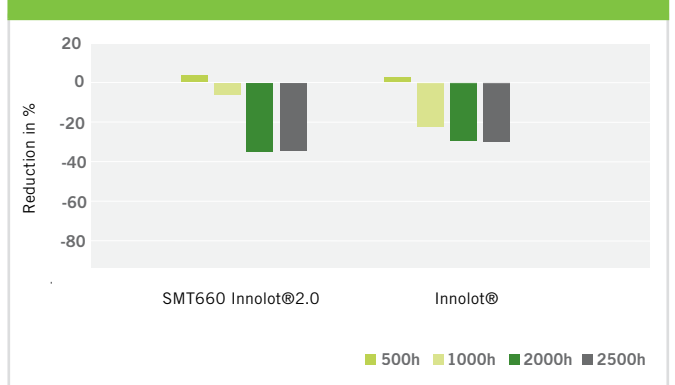
Storage

Temperature	2 - 10 °C
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R1206: Reduction of Shearforce TCT -40/+125 °C



R1206: Reduction of Shearforce TCT 40/+150 °C



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